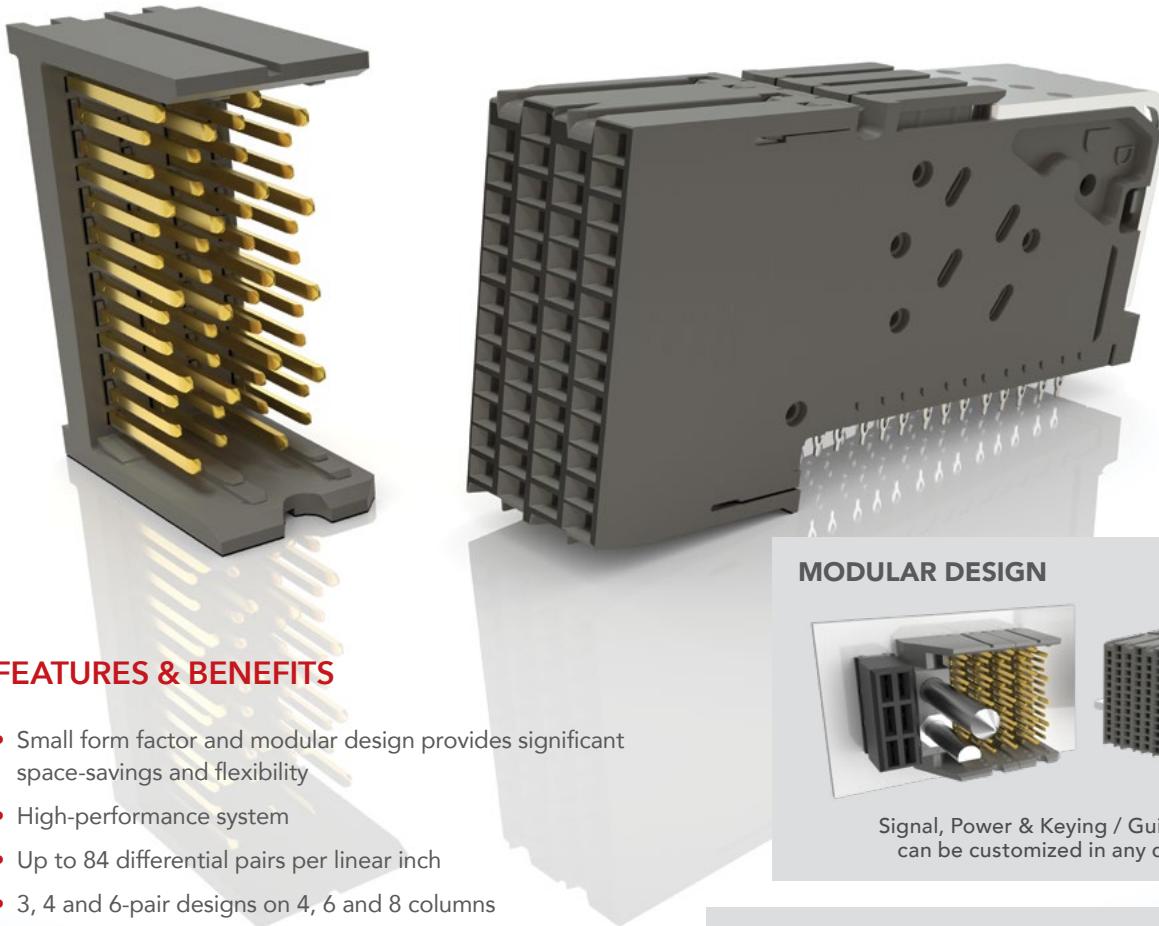


HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

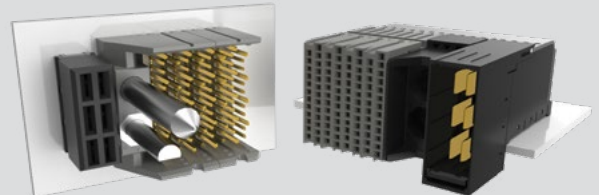
16
Gbps



FEATURES & BENEFITS

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and end walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane
- Press-fit extraction and insertion tool options; please visit samtec.com/tooling for details

MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR



XCede[®] HD
Up to 84 pairs per linear inch



Traditional Backplane
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

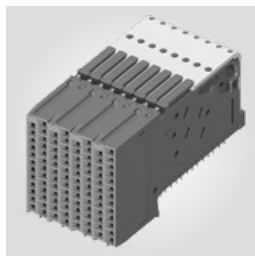
KEY SPECIFICATIONS

PITCH	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE
1.80 mm	LCP	Phosphor Bronze (HDTM Series) Copper Alloy (HDTF & HPTS Series)	Au or Sn over 50 μ" (1.27 μm) Ni	-40 °C to + 105 °C (HDTX Series)

(1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE RECEPTACLE

HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
	-3, -4, -6	-04, -06, -08	-S = 30 μ" (0.76 μm) Gold on Contact Area, Matte Tin on Tail		-LC = Standard -HS = High-Speed	-100 = 100 Ω -085 = 85 Ω

HDTF
Board Mates:
HDTM

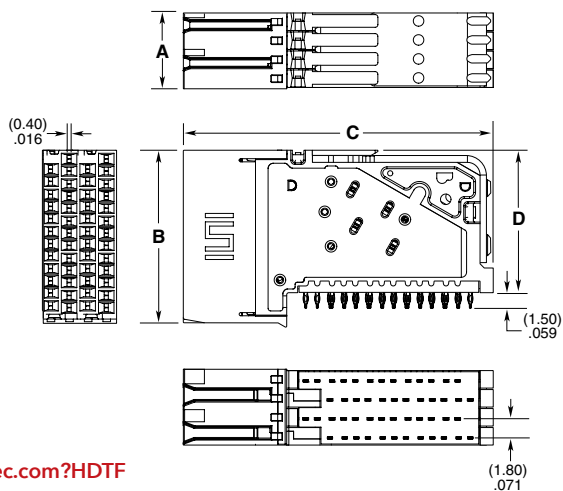


NO. OF COLUMNS	A
-04	(7.2) .28
-06	(10.8) .42
-08	(14.4) .57

PAIRS PER COLUMN	B	C	D
-3	(12.8) .50	(26.0) 1.02	(9.8) .386
-4	(16.4) .64	(29.4) 1.16	(13.5) .53
-6	(23.6) .93	(36.6) 1.44	(20.7) .81

ALSO AVAILABLE

Power and keying/guidance modules also are available but require a single customizable BSP product. Contact HSBP@samtec.com.

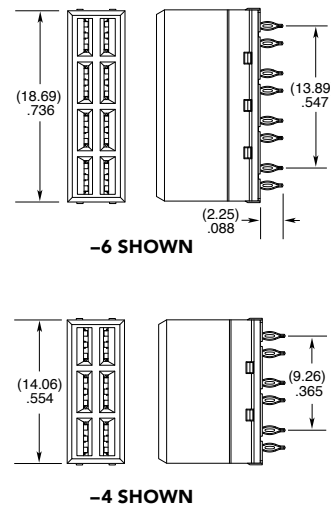
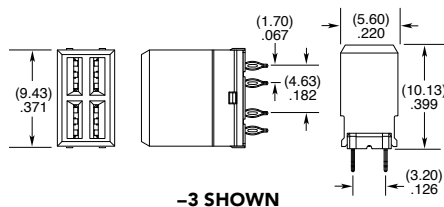
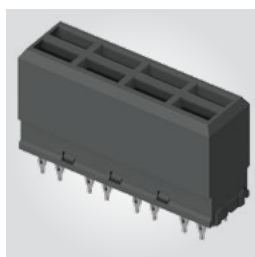


View complete specifications at: samtec.com?HDTF

(3.20 mm) .126" PITCH • HIGH-DENSITY BACKPLANE POWER MODULE

HPTS	BODY HEIGHT	PLATING	D	ORIENTATION
	Based on Pair Count of Signal Modules (HDTF Series). -3 = For use with 3 pair HDTF Series -4 = For use with 4 pair HDTF Series -6 = For use with 6 pair HDTF Series	-S = 30 μ" (0.76 μm) Gold on Contact Area, Matte Tin on Tail		-VT = Vertical

HPTS
Mates with:
BSP
(See HDTF for more information.)



View complete specifications at: samtec.com?HPTS

Notes:
Some lengths, styles and options are non-standard, non-returnable.
XCede[®] is a registered trademark of Amphenol.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [High Speed/Modular Connectors](#) category:

Click to view products by [Samtec](#) manufacturer:

Other Similar products are found below :

[650827-1](#) [74040-1346](#) [1410191-1](#) [1410337-1](#) [1410368-3](#) [1410367-3](#) [1410971-4](#) [1467833-1](#) [2000877-1](#) [2000878-1](#) [2041314-1](#) [2065387-1](#)
[2187307-1](#) [163P](#) [1934290-1](#) [2000875-1](#) [2065799-1](#) [2065917-1](#) [2102736-2](#) [FSR-40](#) [2169868-2](#) [22354-8](#) [437-5040-000](#) [039-0246-000](#)
[0740618502](#) [0761601016](#) [73774-1000](#) [030-2415-003/100 PK](#) [030-7380-004](#) [030-2494-001](#) [532939-1](#) [5532901-3](#) [3-1469268-7](#) [UMK-SE](#)
[11,25-1](#) [74748-102LF](#) [10041743-101LF](#) [10066670-100002LF](#) [1-533915-1](#) [249-4515-000](#) [7-1469373-3](#) [DL2-2J/S](#) [2000713-8](#) [2000713-7](#)
[10124313-101LF](#) [1410189-2](#) [3011-21](#) [EBTF-4-10-2.0-S-RA-1](#) [430305-001](#) [4395800100](#) [8140115](#)